

What is claimed is:

1. An electrolytic tin-plating solution, having a pH value of 1.5 – 6.0 and comprising:
  - (1) 5 – 60 g/L of tin(II) ion,
  - (2) a complexing agent,
  - (3) a surfactant, and
  - (4) 0.01 – 0.5 g/L of bismuth(III) ion
2. The electrolytic tin-plating solution described Claim 1, further comprising a conducting salt, an anode-dissolving agent or an antioxidant.
3. The electrolytic tin-plating solution described Claim 1, wherein the surfactant is a nonionic surfactant.
4. A method for electrolytic tin plating, characterized by using the electrolytic tin-plating solution described Claim 1 for electrolytic tin plating on electronic parts.